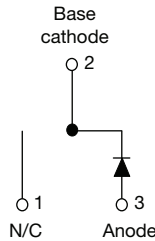
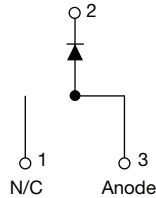


Hyperfast Rectifier, 8 A FRED Pt[®]


D²PAK (TO-263AB)

TO-262AA

VS-8ETH06SHM3

VS-8ETH06-1HM3

LINKS TO ADDITIONAL RESOURCES



3D Models

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	8 A
V_R	600 V
V_F at I_F	1.3 V
t_{rr} typ.	18 ns
T_J max.	175 °C
Package	D ² PAK (TO-263AB), TO-262AA
Circuit configuration	Single

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Peak repetitive reverse voltage	V_{RRM}		600	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 144$ °C	8	A
Non-repetitive peak surge current	I_{FSM}	$T_J = 25$ °C	90	
Peak repetitive forward current	I_{FM}		16	
Operating junction and storage temperatures	T_J, T_{Stg}		-55 to +175	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25$ °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100$ μ A	600	-	-	V
Forward voltage	V_F	$I_F = 8$ A $I_F = 8$ A, $T_J = 150$ °C	-	2.0 1.3	2.4 1.8	
Reverse leakage current	I_R	$V_R = V_R$ rated $T_J = 150$ °C, $V_R = V_R$ rated	-	0.3 55	50 500	μ A
Junction capacitance	C_T	$V_R = 600$ V	-	17	-	pF
Series inductance	L_S	Measured lead to lead 5 mm from package body	-	8.0	-	nH

FEATURES

- Hyperfast recovery time
- Low forward voltage drop
- Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified, meets JESD 201, class 1 whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
 COMPLIANT
 HALOGEN
FREE

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.



DYNAMIC RECOVERY CHARACTERISTICS ($T_C = 25\text{ }^\circ\text{C}$ unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Reverse recovery time	t_{rr}	$I_F = 1\text{ A}$, $di_F/dt = 100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	-	18	22	ns	
		$I_F = 8\text{ A}$, $di_F/dt = 100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	-	20	-		
		$T_J = 25\text{ }^\circ\text{C}$	-	25	-		
		$T_J = 125\text{ }^\circ\text{C}$	-	40	-		
Peak recovery current	I_{RRM}	$T_J = 25\text{ }^\circ\text{C}$	-	2.4	-	A	
		$T_J = 125\text{ }^\circ\text{C}$	-	4.8	-		
Reverse recovery charge	Q_{rr}	$T_J = 25\text{ }^\circ\text{C}$	-	25	-	nC	
		$T_J = 125\text{ }^\circ\text{C}$	-	120	-		
Reverse recovery time	t_{rr}	$T_J = 125\text{ }^\circ\text{C}$	$I_F = 8\text{ A}$ $di_F/dt = 600\text{ A}/\mu\text{s}$ $V_R = 390\text{ V}$	-	33	-	ns
Peak recovery current	I_{RRM}			-	12	-	A
Reverse recovery charge	Q_{rr}			-	220	-	nC

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-65	-	175	$^\circ\text{C}$
Thermal resistance, junction to case per leg	R_{thJC}		-	1.4	2	$^\circ\text{C}/\text{W}$
Thermal resistance, junction to ambient per leg	R_{thJA}	Typical socket mount	-	-	70	
Thermal resistance, case to heatsink	R_{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style D ² PAK (TO-263AB)	8ETH06SH			
		Case style TO-262AA	8ETH06-1H			

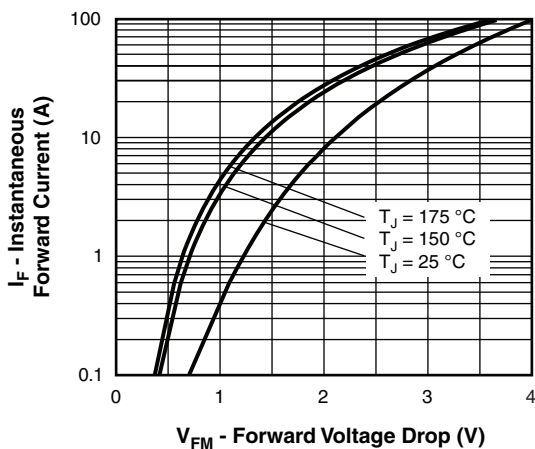


Fig. 1 - Maximum Forward Voltage Drop Characteristics

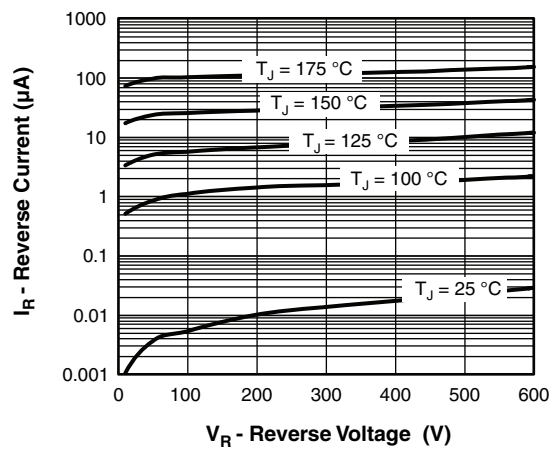


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

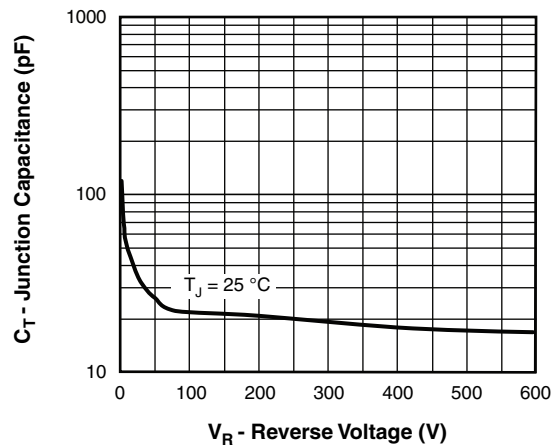


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

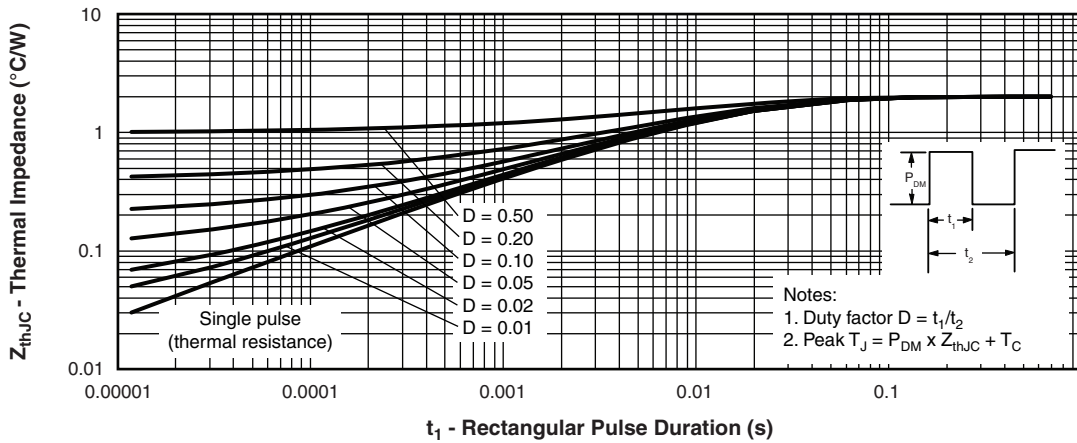


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

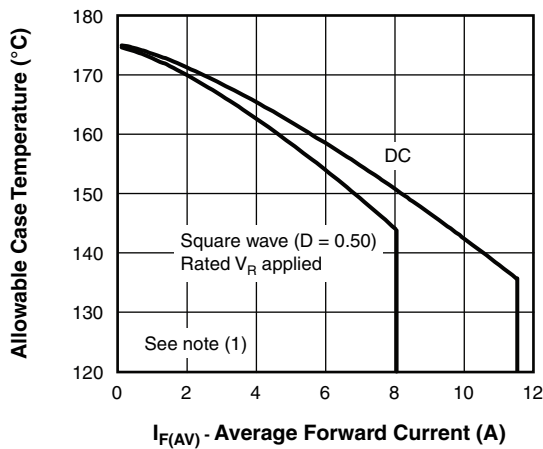


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

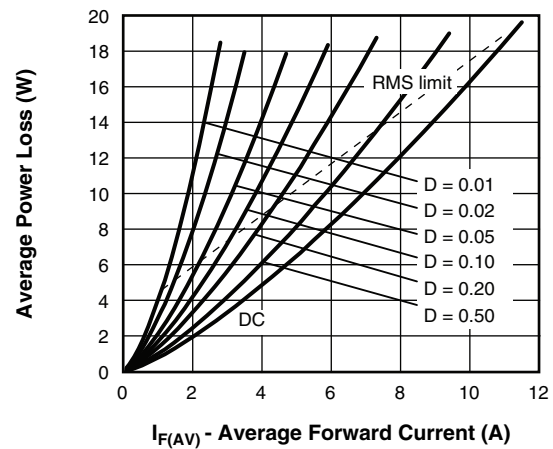


Fig. 6 - Forward Power Loss Characteristics

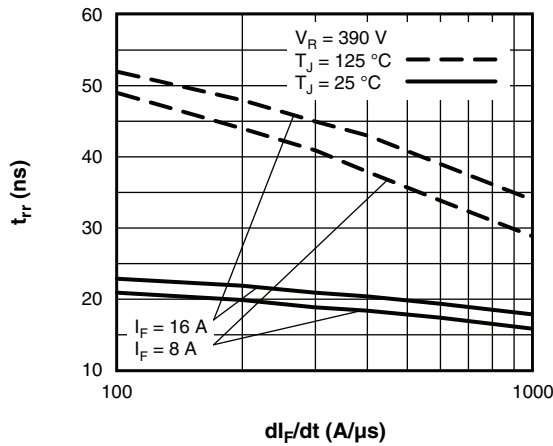


Fig. 7 - Typical Reverse Recovery Time vs. di_F/dt

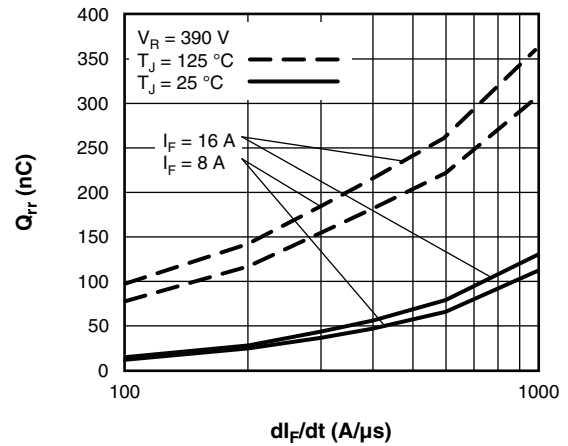
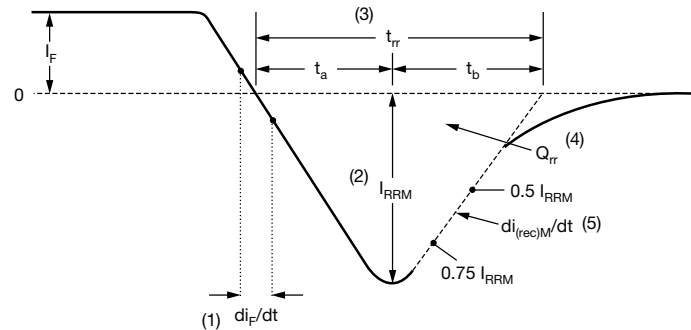


Fig. 8 - Typical Stored Charge vs. di_F/dt

Note

- (1) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$; Pd = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6); Pd_{REV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R



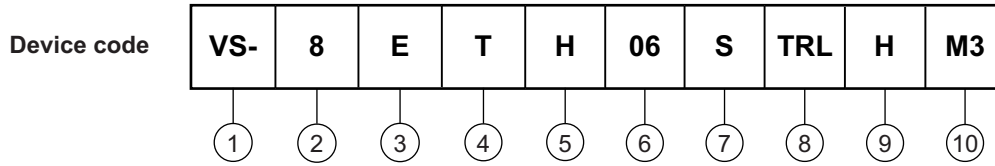
- (1) di_F/dt - rate of change of current through zero crossing
- (2) I_{RRM} - peak reverse recovery current
- (3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current.
- (4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}
- (5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (8 A)
- 3** - E = single diode
- 4** - T = TO-220, D²PAK (TO-263AB)
- 5** - H = hyperfast rectifier
- 6** - Voltage rating (06 = 600 V)
- 7** -
 - S = D²PAK (TO-263AB)
 - -1 = TO-262
- 8** -
 - None = tube (50 pieces)
 - TRL = tape and reel (left oriented, for D²PAK package)
 - TRR = tape and reel (right oriented, for D²PAK package)
- 9** - H = AEC-Q101 qualified
- 10** - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)		
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-8ETH06SHM3	50	Antistatic plastic tube
VS-8ETH06STRRHM3	800	13" diameter reel
VS-8ETH06STRLHM3	800	13" diameter plastic reel
VS-8ETH06-1HM3	50	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS		
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?95046
	TO-262AA	www.vishay.com/doc?95419
Part marking information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444
	TO-262AA	www.vishay.com/doc?95443
Packaging information	D ² PAK (TO-263AB)	www.vishay.com/doc?95032

D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190		D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010		E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039		E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4	e	2.54 BSC		0.100 BSC		
b2	1.14	1.78	0.045	0.070		H	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4	L	1.78	2.79	0.070	0.110	
c	0.38	0.74	0.015	0.029		L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4	L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065		L3	0.25 BSC		0.010 BSC		
D	8.51	9.65	0.335	0.380	2	L4	4.78	5.28	0.188	0.208	

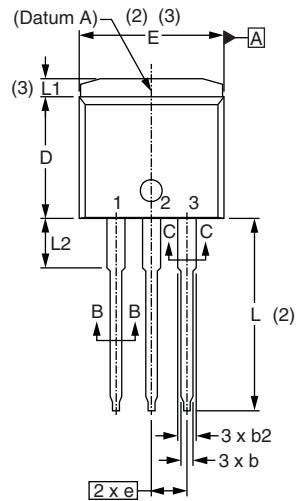
Notes

- Dimensioning and tolerancing per ASME Y14.5 M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- Dimension b1 and c1 apply to base metal only
- Datum A and B to be determined at datum plane H
- Controlling dimension: inch
- Outline conforms to JEDEC® outline TO-263AB

TO-262

DIMENSIONS in millimeters and inches

Modified JEDEC® outline TO-262



$\oplus 0.010 \text{ M} \text{ A} \text{ M} \text{ B}$



Lead assignments

- Diodes**
 1. - Anode (two die)/open (one die)
 2., 4. - Cathode
 3. - Anode



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.36	3.71	0.132	0.146	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline



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